IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re: Park et al.

Serial No.: 10/615,362

Filed: July 8, 2003

METHODS FOR FORMING A METAL CONTACT IN A SEMICONDUCTOR DEVICE IN WHICH AN OHMIC LAYER IS FORMED WHILE FORMING A

BARRIER METAL LAYER

Date: February 17, 2004

Examiner: H. Jey Tsai

Group Art Unit: 2812

Confirmation No.: 8781

Mail Stop Non-Fee Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE TO **ELECTION REQUIREMENT**

Sir:

For:

FEB 1 9 2004

Applicants provide the present Amendment to address the issues raised in the Election Requirement mailed January 20, 2004. Applicants provide the present Amendment pursuant to the rules stated in revised 37 C.F.R. 1.121 that became effective on July 30, 2003.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.